

STP40NF10

N-channel 100 V, 0.025 Ω 50 A TO-220 low gate charge STripFET™ II Power MOSFET

Features

Order code	V _{DSS}	R _{DS(on)} max.	I _D
STP40NF10	100 V	< 0.028 Ω	50 A

- Exceptional dv/dt capability
- Low gate charge
- 100% avalanche tested

Application

Switching applications

Description

This N-channel 100 V Power MOSFET is the latest development of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps allowing remarkable manufacturing reproducibility.

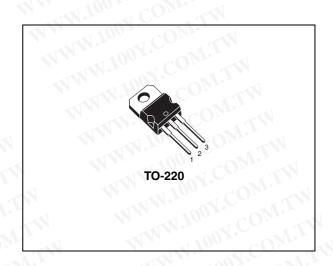


Figure 1. Internal schematic diagram

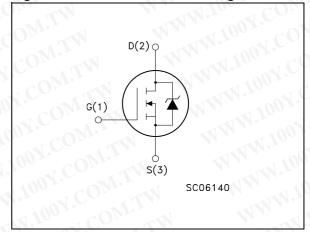


Table 1. Device summary

Order code	Marking	Package	Packaging
STP40NF10	P40NF10@	TO-220	Tube

WWW.100Y.COM.TW HW.100Y.COM.TW W.COM.TW WWW.100V.COM.TW COM.TW Contents STP40NF10 MMM.100X.COM

Contents

COM

1	Electrical ratings	
2	Electrical characteristics	1.T.V.
	2.1 Electrical characteristics (curves)	
3	Test circuit	OM
4	Package mechanical data	
5.1	Revision history	av.cc

WWW.100Y.COM.TW

MMM.100X.COM

WWW.1007.

MMM TOOK COM TW STP40NF10 **Electrical ratings**

Electrical ratings

Table 2. **Absolute maximum ratings**

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage (V _{GS} = 0)	100	V
V _{GS}	Gate- source voltage	±20	V
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	50	Α
I _D	Drain current (continuous) at T _C = 100 °C	35	_ A
I _{DM} ⁽²⁾	Drain current (pulsed)	200	Α
P _{TOT}	Total dissipation at T _C = 25 °C	150	W
	Derating factor	W. Too N.Com	W/°C
dv/dt ⁽³⁾	Peak diode recovery voltage slope	27	V/ns
E _{AS} (4)	Single pulse avalanche energy	385	mJ
T _{stg}	Storage temperature	1 100	°C
Tj	Max. operating junction temperature	- 55 to 175	
2. Pulse v	by wire bonding vidth limited by safe operating area A, di/dt ≤600 A/μs, V _{DD} ≤V _{(BR)DSS} , T _j ≤T _{JMAX} .	MMM.100X	COM

- Limited by wire bonding
- 2. Pulse width limited by safe operating area
- $I_{SD} \leq 50 \text{ A, di/dt} \leq 600 \text{ A/µs, } V_{DD} \leq V_{(BR)DSS}, T_j \leq T_{JMAX}.$
- Starting T_i = 25 °C, I_D = 50 A, V_{DD} =25 V

Table 3. Thermal data

WWW.100Y.COM.

	A, di/dt \leq 600 A/µs, V _{DD} \leq V _{(BR)DSS} , T _j \leq T _{JMAX} . T _j = 25 °C, I _D = 50 A, V _{DD} =25 V Thermal data		
1			
Symbol	Parameter	Value	Unit
Symbol R _{thj-case}	Parameter Thermal resistance junction-case max	Value 1	°C/W
1 ()))		Value 1 62.5	The Con

WWW.100Y.COM.TW

MMM.100X.COM

MMM.1001

MMM.100Y.COM.TM N.100Y.COM.TW **Electrical characteristics** STP40NF10

Electrical characteristics 2

NW.100Y.COM.TW (T_{CASE} = 25 °C unless otherwise specified)

On/off states Table 4.

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown voltage	$I_D = 250 \ \mu\text{A}, \ V_{GS} = 0$	100	W.I.A		V
I _{DSS}	Zero gate voltage Drain current (V _{GS} = 0)	V_{DS} = Max rating V_{DS} =Max rating, T_{C} =125°C	S.Co	OM.T	10	μ Α μ Α
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ±20 V	1007	$CO_{N_{I}}$	±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 25 A	11.10	0.025	0.028	Ω
Table 5.	Dynamic	ON.TW WY	NW.	007	COM	
			1	1	1.00	

Table 5. **Dynamic**

Symbol		Test conditions	Min.	Тур.	Max.
9 _{fs} (1)	Forward transconductance	$V_{DS} = 15 V_{,} I_{D} = 28 A$	N	22	101.
C _{iss}	Input capacitance	N.T.		2180	nov.
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$		298	100
C_{rss}	Reverse transfer capacitance	$V_{GS} = 0$		83.7	110
Q_g	Total gate charge	$V_{DD} = 50 \text{ V}, I_D = 40 \text{ A},$		46.5	62
Q_{gs}	Gate-source charge	V _{GS} = 10V	-	13.3	MN.
Q_{gd}	Gate-drain charge	(see Figure 15)		17.5	22.5

^{1.} Pulsed: Pulse duration = 300 μs, duty cycle 1.5.

WWW.100 **Switching times**

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on delay time Rise time	$V_{DD} = 50V, I_{D} = 25A$ $R_{G} = 4.7\Omega V_{GS} = 10V$		21 46	-	ns ns
t _{d(off)}	Turn-off-delay time Fall time	(see Figure 14)	COM	54 13	-	ns ns

WWW.100Y.COM.TW

WWW.100Y.COM.T

Table 7.

COMITY

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)	MM.1007.CO	1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	V	80 320	A A
V _{SD} (2)	Forward on voltage	I _{SD} = 50A, V _{GS} = 0	1.1		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 50A, V_{DD} = 25V$ $di/dt = 100A/\mu s,$ $T_j = 150^{\circ}C$ (see Figure 16)		80 250 6.4	7	ns nC A

WWW.100Y.COM.TW

W.100Y.COM.TW

TCON.TW

WWW.100X.

M.M.M. 100X COM.TW

WWW.TOOX.COM.TW

MMM.100X.COM

^{1.} Pulse width limited by safe operating area.

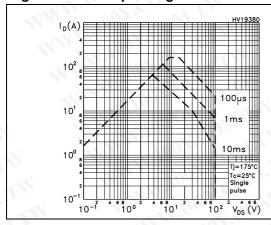
Pulsed: Pulse duration = 300 µs, duty cycle 1.5% WWW.100Y.COM.

Electrical characteristics STP40NF10

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220

Figure 3. Thermal impedance for TO-220



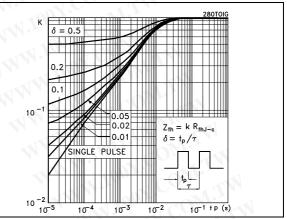
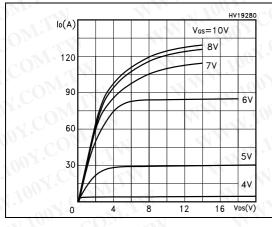


Figure 4. Output characteristics

Figure 5. Transfer characteristics



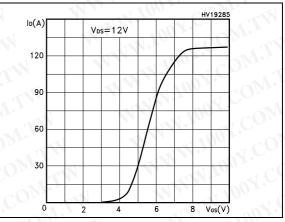
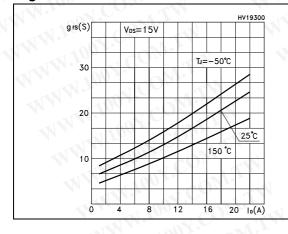
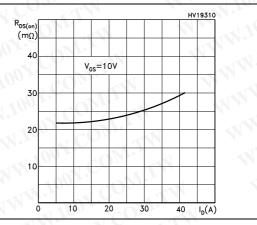


Figure 6. Transconductance

Figure 7. Static drain-source on resistance





MMM.100X.COM

HV19320 HV19330 C(pF) f=1MHz 3000 V_{GS}=0V Vps=50V 12 ID=40A Ciss 2000 1000 10 20 30 40 50 Og(nC) 20 30 40 Vos(V)

Gate charge vs. gate-source voltage Figure 9. **Capacitance variations**

Figure 10. Normalized gate threshold voltage Figure 11. Normalized on resistance vs. vs. temperature

temperature

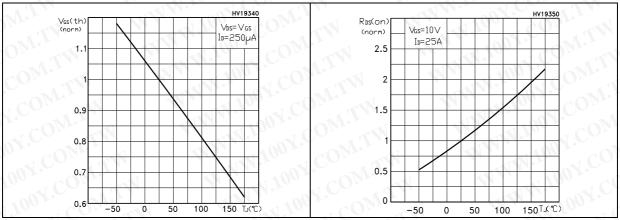
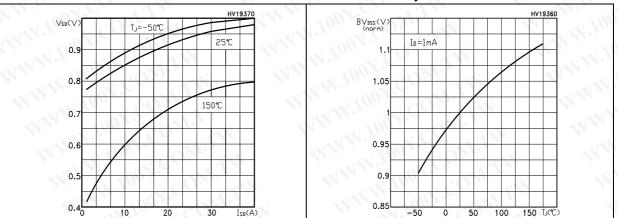


Figure 12. Source-drain diode forward characteristics

Normalized breakdown voltage vs. Tj



M.M.N. 100 N. COM

Test circuit STP40NF10

3 Test circuit

Figure 14. Switching times test circuit for resistive load

Figure 15. Gate charge test circuit

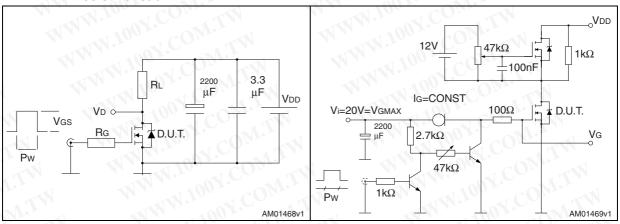


Figure 16. Test circuit for inductive load switching and diode recovery times

Figure 17. Unclamped Inductive load test circuit

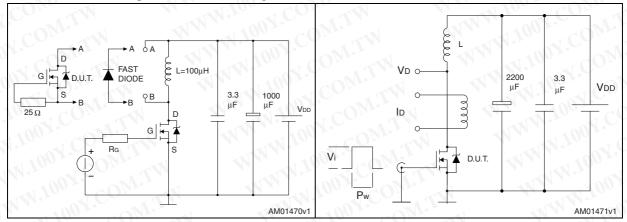
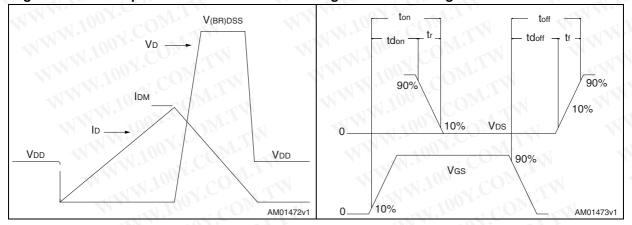


Figure 18. Unclamped inductive waveform

Figure 19. Switching time waveform



MMM.100X.CON

Package mechanical data 4

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

MMM 100X COM TW

N.100Y.COM.TW

CON.TW

WWW.100

MMM.1004.COJ

M.M.M. TOOX COM TW

WWW.100X.

WIOON.COM.TW

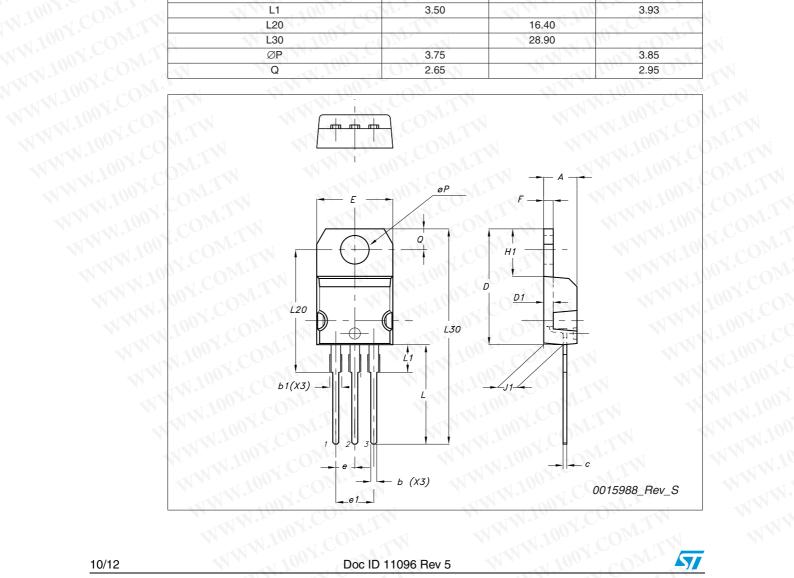
WWW.100Y.COM

WWW.100Y.C

TO-220 type A mechanical data

MMM.100X.COM.TM

100,100	10	mm	
Dim	Min	Тур	Max
CA	4.40	A CONTRACT	4.60
b D	0.61	100, 000,	0.88
b1	1.14		1.70
c	0.48	1 100 CON	0.70
D	15.25	.003	15.75
D1 C		1.27	
10E . ON.	10	1007	10.40
е	2.40	AT NO.	2.70
e1	4.95	1100	5.15
F	1.23		1.32
H1	6.20	1100	6.60
J1	2.40	1111	2.72
L	13		14
1 100 x	3.50	100	3.93
L20		16.40	
L30	COM	28.90	30
ØP	3.75		3.85
Q	2.65		2.95



WWW.1007.

MMM.100X.COW

WWW.100Y.COM.TW NW.100Y.COM.TW A CONTIN STP40NF10 **Revision history** MMM.100X.COM MMM.100

Revision history WWW.

Table 8.

Date	Revision	Changes
16-Dec-2004	1.	First version.
17-Aug-2006	2	The document has been reformatted.
31-Jan-2007	3	Typo mistake on <i>Table 2</i> .
19-Sep-2007	C4	Added DPAK.
10-Nov-2010	5	Removed DPAK.

WWW.100X.

WWW.100Y.COM.TW

MMM.100X.COM

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

12/12 Doc ID 11096 Rev 5